

Please amend the paragraph in the specification as follows:

ABSTRACT

A plant package comprising a pot covered with a plant cover, the plant cover at least comprising a base portion, and optionally having a skirt or a detachable upper portion. ~~The plant cover has a heat shrinkable bonding material for heat shrinking to secure the plant cover about the pot.~~

[0001] The present application is a continuation of U.S. Serial No. 10/325,103, filed December 19, 2002, now U.S. Patent No. 6,691,458, which is a continuation of U.S. Serial No. 10/051,116, filed January 17, 2002, now U.S. Patent No. 6,701,667, which is a continuation of 09/895,302, filed June 29, 2001, now U.S. Patent No. 6,343,456, which is a continuation of U.S. Serial No. 09/626,375, filed July 26, 2000, now abandoned; which is a continuation of U.S. Serial No. 09/366,630, filed August 3, 1999, now U.S. Patent No. 6,192,657; which is a continuation of U.S. Serial No. 09/025,090, filed February 17, 1998, now U.S. Patent No. 5,930,979; which is a continuation of U.S. Serial No. 08/775,516, filed January 2, 1997, now U.S. Patent No. 5,740,658; which is a continuation of U.S. Serial No. 08/460,180, filed June 2, 1995, now U.S. Patent No. 5,617,703; which is a continuation of U.S. Serial No. 08/237,078, filed May 3, 1994, now U.S. Patent No. 5,625,979, issued on May 6, 1997; which is a continuation-in-part of U.S. Serial No. 08/220,852, filed March 31,

1994, now U.S. Patent No. 5,572,851. Each of the applications listed above is hereby expressly incorporated by reference herein in its entirety.